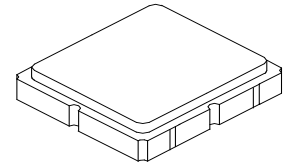


- *Narrow-band SAW Filter*
- *Balanced/Single-ended Operation*
- *3.8 x 3.8 x 1.4 mm Surface-mount Package*
- *Complies with Directive 2002/95/EC (RoHS)*



**SF2344D**

**241 MHz  
SAW Filter**



**SM3838-8**

**Absolute Maximum Ratings**

Rating	Value	Units
Maximum Incident Power in Passband, Continuous	+15	dBm
Maximum DC Voltage on any Non-ground Terminals	3	VDC
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260 °C for 30 s	

**Electrical Characteristics**

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	$f_C$			241		MHz
Minimum Insertion Loss	$IL_{MIN}$			2.2	3.3	dB
3 dB Bandwidth	$BW_3$			5		MHz
Amplitude Ripple 240.9 to 241.1 MHz					0.2	dB <sub>P-P</sub>
Group Delay Ripple 240.9 to 241.1 MHz					0.2	µs <sub>P-P</sub>
Rejection Referenced to $IL_{MIN}$ :						dB
10 to 232.5 MHz			50	60		
274 to 886.5 MHz			50	60		
Operating Temperature Range			-10		+85	°C

Case Style	SM3838-8 3.8 x 3.8 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	B09, <u>YWWS</u>					
Standard Reel Quantity	Reel Size 7 Inch					500 Pieces/Reel
	Reel Size 13 Inch					3000 Pieces/Reel

**Electrical Connections**

Connection	Terminals
50 Ω Input Port	2
200 Ω Balanced Output Port	6, 7
Ground	All others

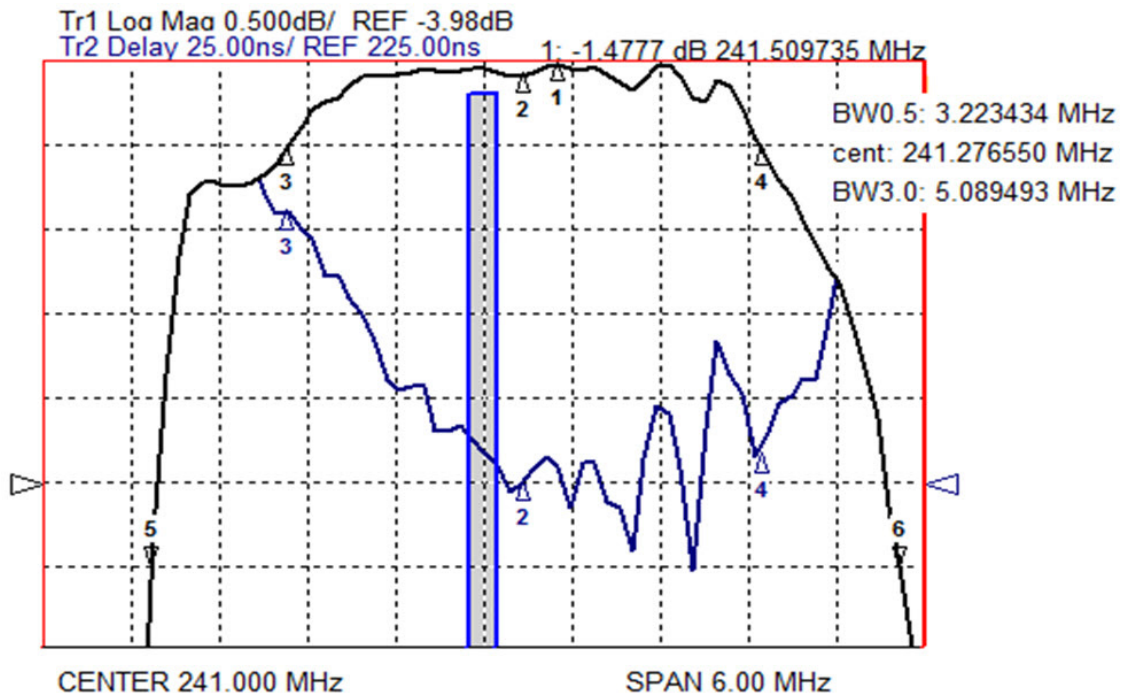
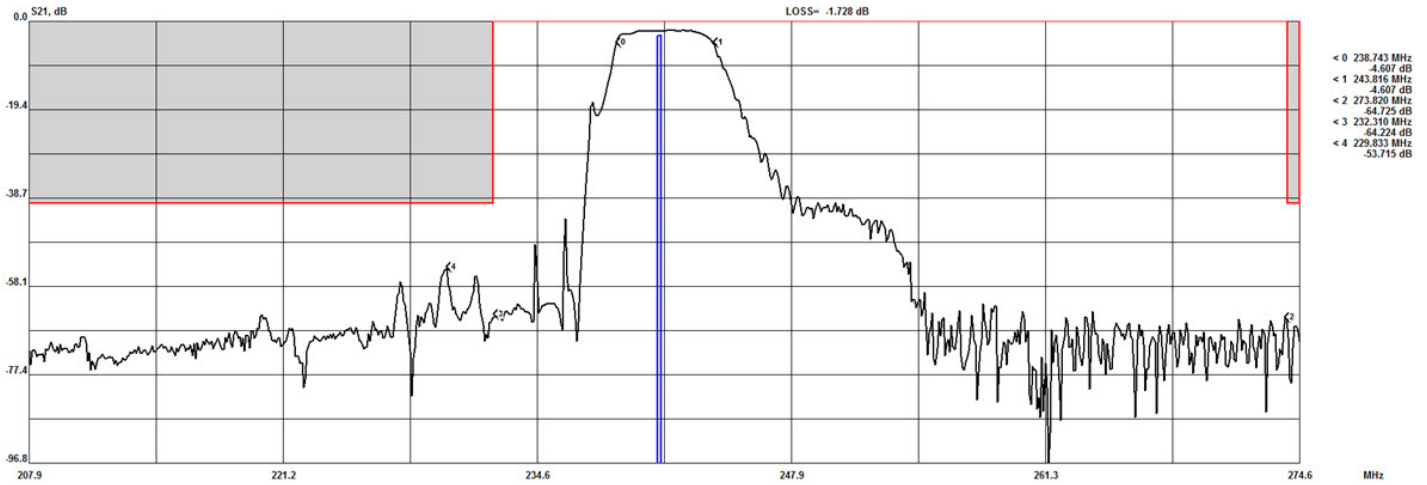


**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

**NOTES:**

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

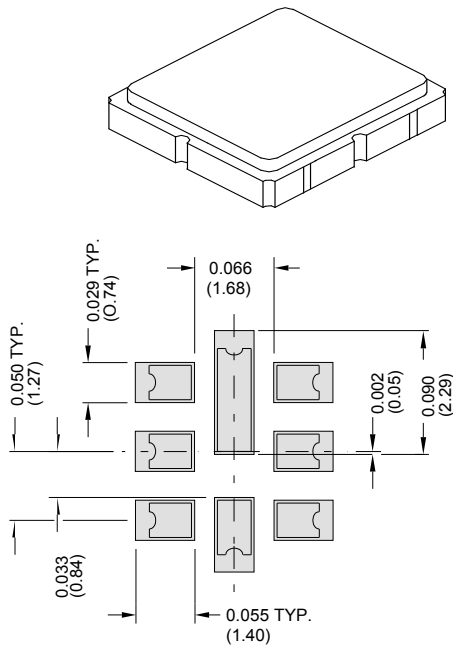
# Filter Response Plots



# SM3838-8 Case

## 8-Terminal Ceramic Surface-mount Case

### 3.8 X 3.8 mm Nominal Footprint



Typical PCB Land Footprint

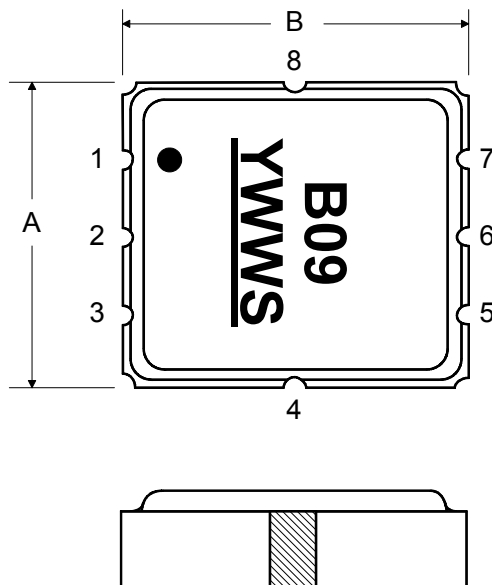
#### Case Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.6	3.8	4.0	0.142	0.150	0.157
B	3.6	3.8	4.0	0.142	0.150	0.157
C	1.05	1.20	1.40	0.041	0.047	0.055
D	0.95	1.10	1.25	0.037	0.043	0.049
E	0.90	1.00	1.10	0.035	0.040	0.043
F	0.50	0.60	0.70	0.020	0.024	0.028
G	2.39	2.54	2.69	0.090	0.100	0.110
H	1.40	1.75	2.05	0.055	0.069	0.080

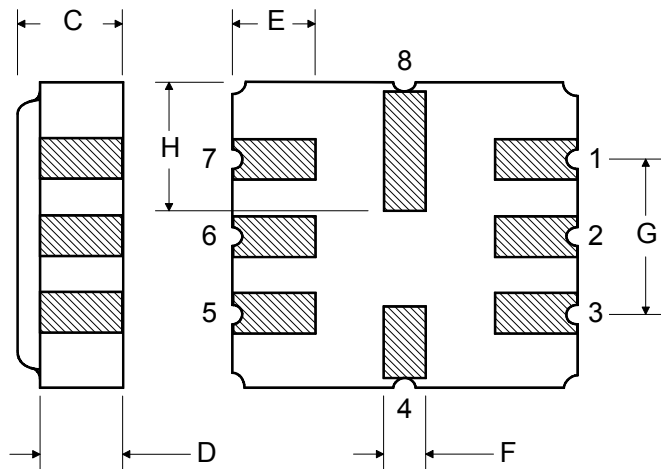
#### Materials

Solder Pad Plating	0.3 to 1.0 $\mu\text{m}$ Gold over 1.27 to 8.89 $\mu\text{m}$ Nickel
Lid Plating	2.0 to 3.0 $\mu\text{m}$ Nickel
Body	$\text{Al}_2\text{O}_3$ Ceramic
Pb Free	

#### TOP VIEW

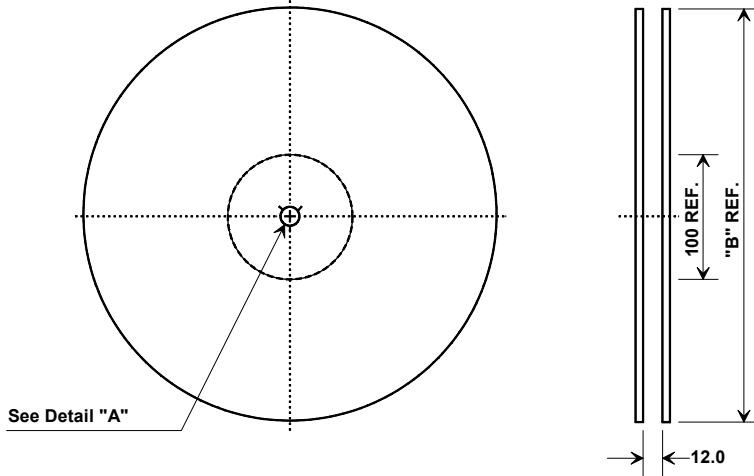


#### BOTTOM VIEW

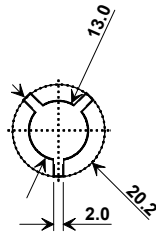


## Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA-481

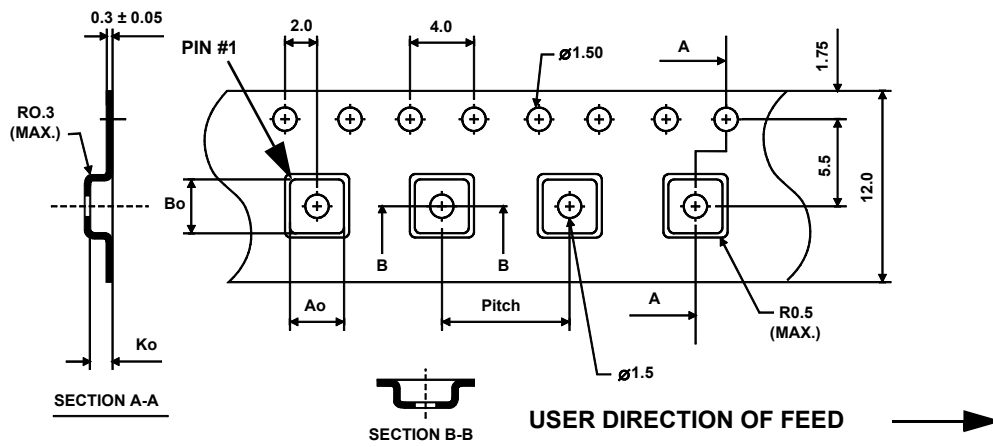


"B"		Quantity Per Reel
Nominal Size		
Inches	millimeters	
7	178	500
13	330	3000



### COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	4.25 mm
Bo	4.25 mm
Ko	1.30 mm
Pitch	8.0 mm
W	12.0 mm



## Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

